

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Myunghye Kim	11/08/2012
RECEIVING PARTY DATA	
Name:	Soko Kagaku Co., Ltd.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13700667
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ATTORNEY DOCKET NUMBER:	MASA 1001-1
NAME OF SUBMITTER:	James F. Hann
Total Attachments: 2 source=00350310#page1.tif source=00350310#page2.tif	

OP \$40.00 13700667

**SOLE TO CORPORATE  
ASSIGNMENT**

WHEREAS, the undersigned,

Myungbee Kim  
c/o Soko Kagaku Co., Ltd.  
14th Building, Meijo University  
1-501, Shiogamaguchi, Tempaku-ku  
Nagoya-shi, Aichi 4680073 Japan

hereinafter termed "Inventor", has invented certain new and useful improvements in

**METHOD OF PRODUCING TEMPLATE FOR EPITAXIAL  
GROWTH AND NITRIDE SEMICONDUCTOR DEVICE**

and

and are filing a U.S. Patent Application herewith, which application is a national filing of an International application identifying the above invention on 07 June 2010 as PCT/JP2010/059589 (hereinafter termed "applications"); and

WHEREAS, Soko Kagaku Co., Ltd., a corporation of Japan, having a place of business at 14th Building, Meijo University, 1-501, Shiogamaguchi, Tempaku-ku, Nagoya-shi, Aichi 4680073 Japan (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor to have been received in full from said Assignee:

1. Said Inventor does hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial design) on said invention pursuant to US law, the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the application; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventor hereby covenants and agrees to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in

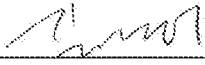
the United States and foreign countries. Such cooperation by said Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional application covering said invention; (d) for filing and prosecuting application for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any application therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall insure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor, the inventor's respective heirs, legal representatives and assigns.

4. Said Inventor hereby warrants and represents that said inventor has not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said inventor hereby authorizes any of the following attorneys and agents: Mark A. Haynes, Ernest J. Beffel, Jr., Warren S. Wolfeld, James P. Hamm, Kenta Suzue, Ryan Davis, and Yiding Wu to (a) insert the date of execution of the oath or declaration of inventorship, and (b) insert the application number and filing date of this application when known.

IN WITNESS WHEREOF, said Inventor has executed and delivered this instrument to said Assignee as of the date written below.

  
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Myunghae KIM

Date: Nov. 08 2012